

ABSTRACT

Plating apparatus and plating method that can plate more uniformly on a processing surface of a workpiece are provided. The plating apparatus is comprised of a plating solution bath which is provided with a first electrode held in a state soaked in a plating solution; a workpiece holding mechanism which holds a workpiece to contact its processing surface to the plating solution; and a contact member, disposed in the workpiece holding mechanism, that electrically contacts with the circumferential edge of the workpiece so to form a conductive layer on the workpiece surface as a second electrode. The contact member is divided along the circumferential direction of the workpiece with which they are electrically contacted. Thus, even if the contact resistance between each section of the contact member with the workpiece is variable, it is possible to adjust the plating electric current for each section of the contact member.